EXTERNAL VERIFICATION OF PACKAGE PROCESSED LINEWIDTHS AND SPACINGS IN SEMICONDUCTOR PACKAGES

Abstract

Disclose is a method that forms non-functional test structures in kerf regions outside functional wiring modules of the ceramic greensheets and across edges of the functional wiring modules, and an associated structure. In order to check or test the spacing and size of wires in functional wiring modules, the invention only needs to examine the non-functional test structures as exposed by cutting the multi-module greensheet along the laminate trim line or by dicing of the greensheet into individual modules. The non-functional wires have the same design spacing, size, and angles as wires in the functional wiring modules. Therefore, the non-functional test structures comprise representative wires of wires in the functional wiring modules.